

# 74HC237-Q100

3-to-8 line decoder, demultiplexer with address latches

Rev. 1 — 14 January 2013

Product data sheet

## 1. General description

The 74HC237-Q100 is a 3-to-8 line decoder, demultiplexer with latches at the three address inputs ( $A_n$ ). The 74HC237-Q100 essentially combines the 3-to-8 decoder function with a 3-bit storage latch. When the latch is enabled ( $\overline{LE} = \text{LOW}$ ), the 74HC237-Q100 acts as a 3-to-8 active LOW decoder. When the latch enable ( $\overline{LE}$ ) goes from LOW-to-HIGH, the last data present at the inputs before this transition, is stored in the latches. Further address changes are ignored as long as  $\overline{LE}$  remains HIGH. The output enable input ( $\overline{E1}$  and  $E2$ ) controls the state of the outputs independent of the address inputs or latch operation. All outputs are HIGH unless  $\overline{E1}$  is LOW and  $E2$  is HIGH. The 74HC237-Q100 is ideally suited for implementing non-overlapping decoders in 3-state systems and strobed (stored address) applications in bus-oriented systems.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

## 2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
  - ◆ Specified from  $-40\text{ }^{\circ}\text{C}$  to  $+85\text{ }^{\circ}\text{C}$  and from  $-40\text{ }^{\circ}\text{C}$  to  $+125\text{ }^{\circ}\text{C}$
- Combines 3-to-8 decoder with 3-bit latch
- Multiple input enable for easy expansion or independent controls
- Active HIGH mutually exclusive outputs
- Low-power dissipation
- Complies with JEDEC standard no. 7A
- ESD protection:
  - ◆ MIL-STD-883, method 3015 exceeds 2000 V
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V ( $C = 200\text{ pF}$ ,  $R = 0\text{ }\Omega$ )

## 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74HC237D-Q100	$-40\text{ }^{\circ}\text{C}$ to $+125\text{ }^{\circ}\text{C}$	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1



### 4. Functional diagram

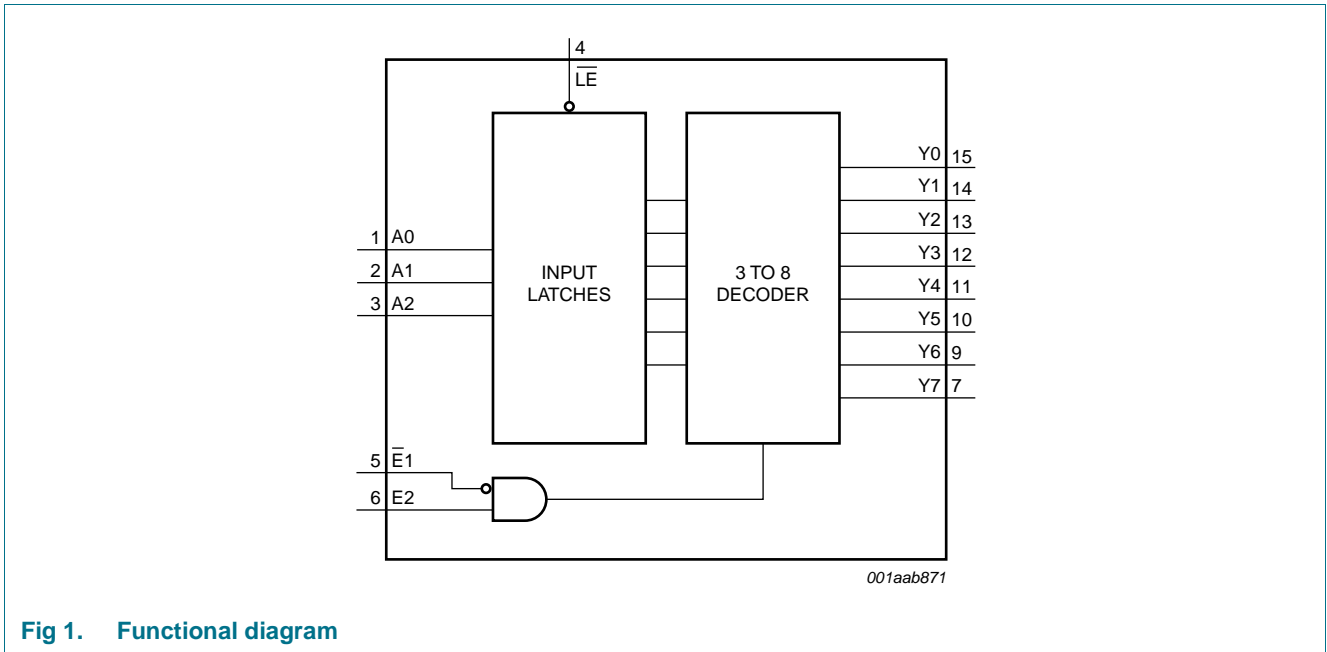


Fig 1. Functional diagram

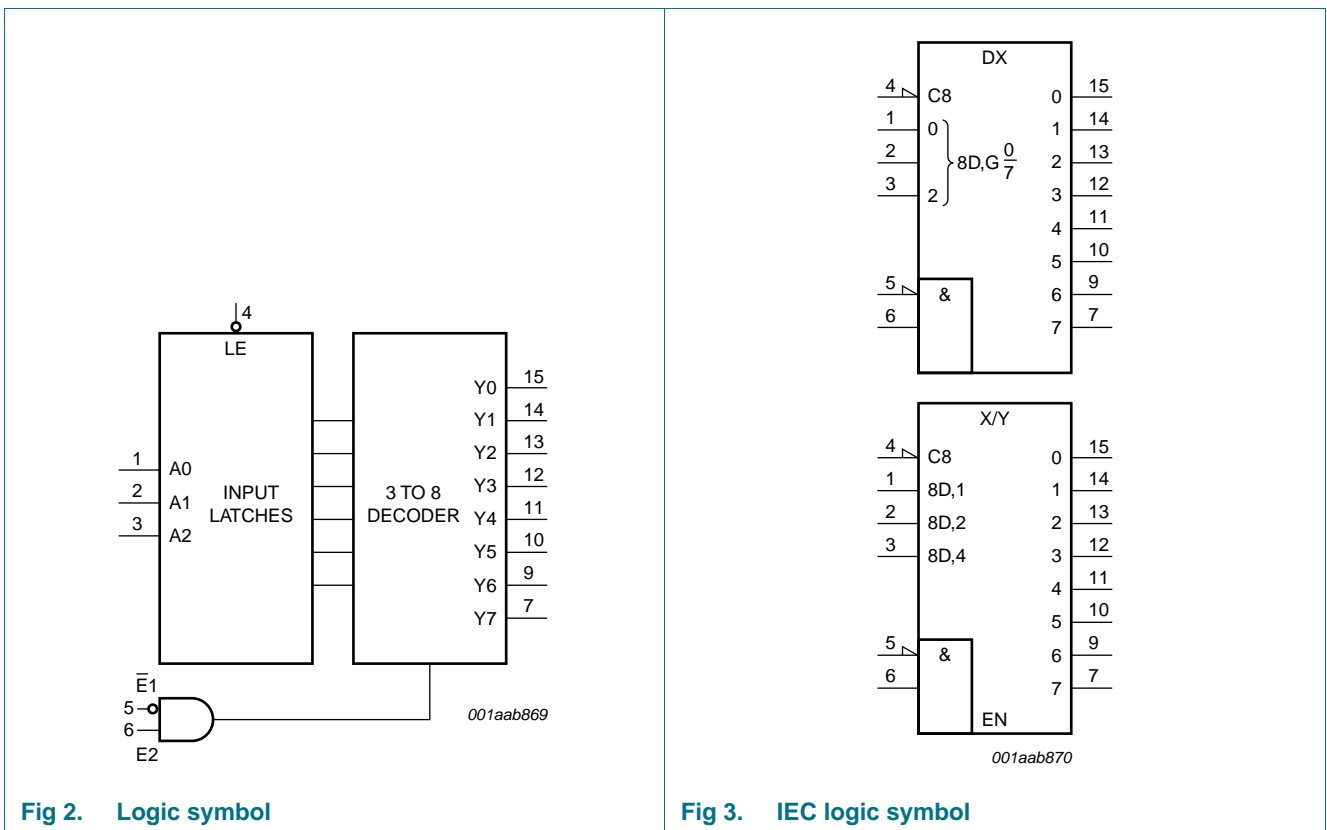


Fig 2. Logic symbol

Fig 3. IEC logic symbol

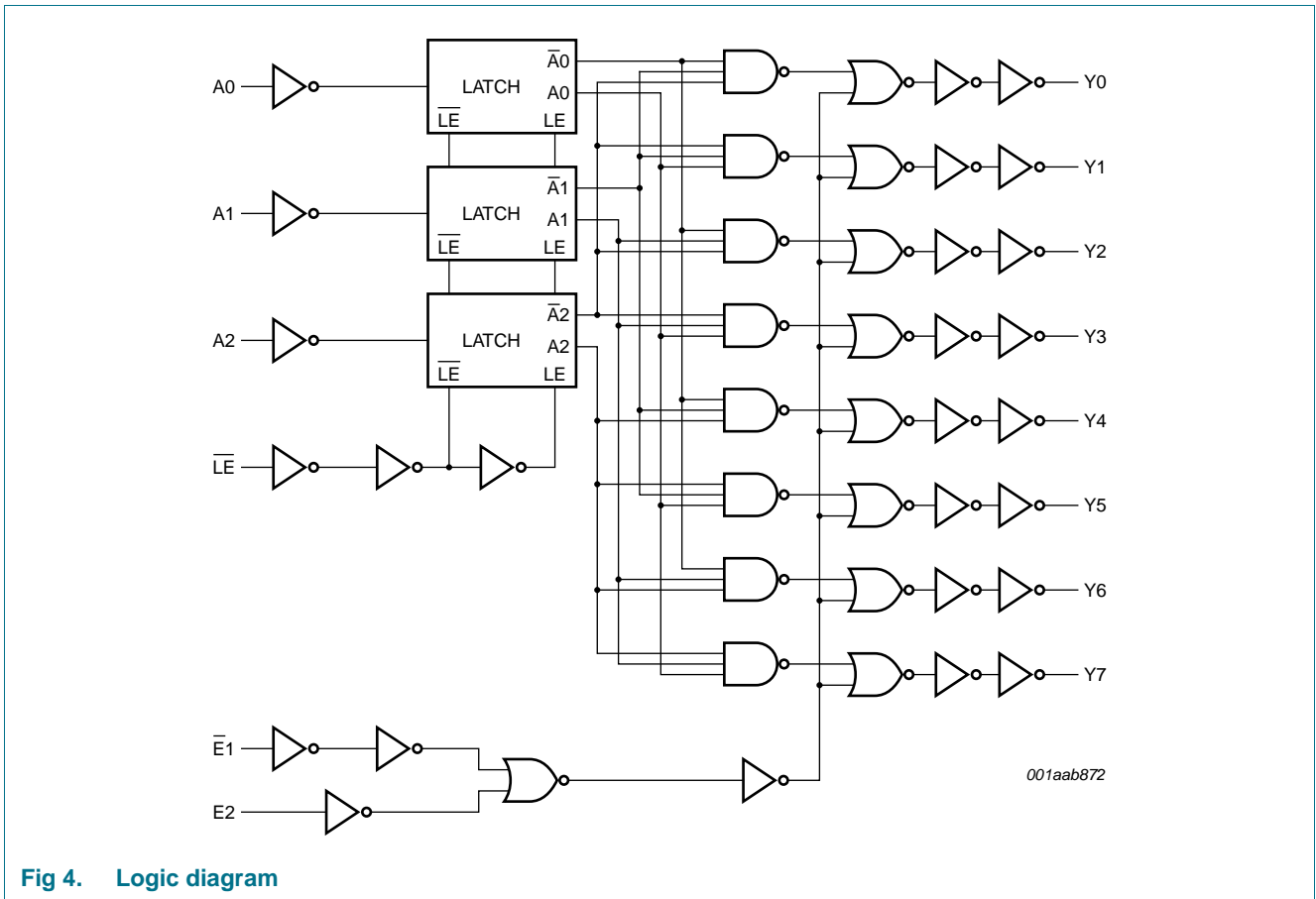


Fig 4. Logic diagram

## 5. Pinning information

### 5.1 Pinning

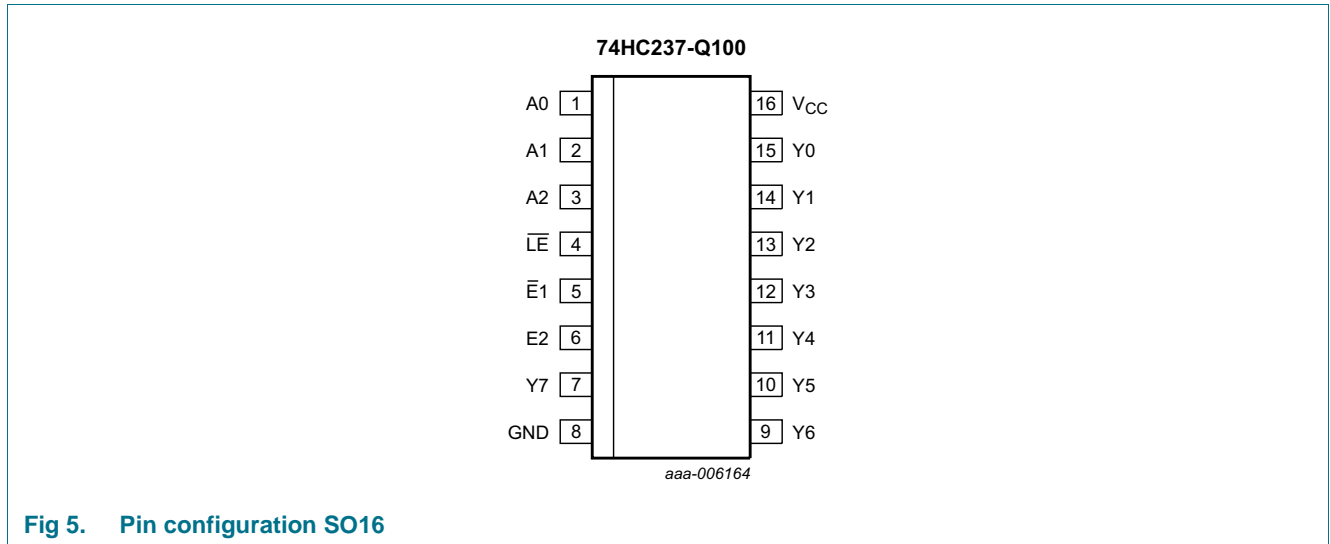


Fig 5. Pin configuration SO16

### 5.2 Pin description

Table 2. Pin description

Symbol	Pin	Description
A0 to A2	1, 2, 3	data input
$\overline{LE}$	4	latch enable input (active LOW)
$\overline{E1}$	5	data enable input 1 (active LOW)
E2	6	data enable input 2 (active HIGH)
Y0 to Y7	15, 14, 13, 12, 11, 10, 9, 7	output
GND	8	ground (0 V)
V <sub>CC</sub>	16	supply voltage

## 6. Functional description

Table 3. Function table

Enable			Input			Output							
$\overline{LE}$	$\overline{E1}$	E2	A0	A1	A2	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
H	L	H	X	X	X	stable							
X	H	X	X	X	X	L	L	L	L	L	L	L	L
X	X	L	X	X	X	L	L	L	L	L	L	L	L
L	L	H	L	L	L	H	L	L	L	L	L	L	L
L	L	H	H	L	L	L	H	L	L	L	L	L	L
L	L	H	L	H	L	L	L	H	L	L	L	L	L
L	L	H	H	H	L	L	L	L	H	L	L	L	L
L	L	H	L	L	H	L	L	L	L	H	L	L	L
L	L	H	H	L	H	L	L	L	L	L	H	L	L
L	L	H	L	H	H	L	L	L	L	L	L	H	L
L	L	H	H	H	H	L	L	L	L	L	L	L	H

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

## 7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+7	V
$I_{IK}$	input clamping current	$V_I < -0.5\text{ V}$ or $V_I > V_{CC} + 0.5\text{ V}$	-	$\pm 20$	mA
$I_{OK}$	output clamping current	$V_O < -0.5\text{ V}$ or $V_O > V_{CC} + 0.5\text{ V}$	-	$\pm 20$	mA
$I_O$	output current	$V_O = -0.5\text{ V}$ to $(V_{CC} + 0.5\text{ V})$	-	$\pm 25$	mA
$I_{CC}$	supply current		-	+50	mA
$I_{GND}$	ground current		-	-50	mA
$T_{stg}$	storage temperature		-65	+150	°C
$P_{tot}$	total power dissipation		[1]	500	mW

[1] For SO16 package:  $P_{tot}$  derates linearly with 8 mW/K above 70 °C.

## 8. Recommended operating conditions

Table 5. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		2.0	5.0	6.0	V
$V_I$	input voltage		0	-	$V_{CC}$	V
$V_O$	output voltage		0	-	$V_{CC}$	V
$T_{amb}$	ambient temperature		-40	+25	+125	°C

**Table 5. Recommended operating conditions ...continued**  
 Voltages are referenced to GND (ground = 0 V) ...continued

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 2.0\text{ V}$	-	-	625	ns/V
		$V_{CC} = 4.5\text{ V}$	-	1.67	139	ns/V
		$V_{CC} = 6.0\text{ V}$	-	-	83	ns/V

## 9. Static characteristics

**Table 6. Static characteristics**

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ }^{\circ}\text{C}$			$T_{amb} = -40\text{ }^{\circ}\text{C to } +85\text{ }^{\circ}\text{C}$		$T_{amb} = -40\text{ }^{\circ}\text{C to } +125\text{ }^{\circ}\text{C}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 2.0\text{ V}$	1.5	1.2	-	1.5	-	1.5	-	V
		$V_{CC} = 4.5\text{ V}$	3.15	2.4	-	3.15	-	3.15	-	V
		$V_{CC} = 6.0\text{ V}$	4.2	3.2	-	4.2	-	4.2	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 2.0\text{ V}$	-	0.8	0.5	-	0.5	-	0.5	V
		$V_{CC} = 4.5\text{ V}$	-	2.1	1.35	-	1.35	-	1.35	V
		$V_{CC} = 6.0\text{ V}$	-	2.8	1.8	-	1.8	-	1.8	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 2.0\text{ V}$	1.9	2.0	-	1.9	-	1.9	-	V
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 4.5\text{ V}$	4.4	4.5	-	4.4	-	4.4	-	V
		$I_O = -20\text{ }\mu\text{A}; V_{CC} = 6.0\text{ V}$	5.9	6.0	-	5.9	-	5.9	-	V
		$I_O = -4.0\text{ mA}; V_{CC} = 4.5\text{ V}$	3.98	4.32	-	3.84	-	3.7	-	V
		$I_O = -5.2\text{ mA}; V_{CC} = 6.0\text{ V}$	5.48	5.81	-	5.34	-	5.2	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$								
		$I_O = 20\text{ }\mu\text{A}; V_{CC} = 2.0\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20\text{ }\mu\text{A}; V_{CC} = 4.5\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 20\text{ }\mu\text{A}; V_{CC} = 6.0\text{ V}$	-	0	0.1	-	0.1	-	0.1	V
		$I_O = 4.0\text{ mA}; V_{CC} = 4.5\text{ V}$	-	0.15	0.26	-	0.33	-	0.4	V
		$I_O = 5.2\text{ mA}; V_{CC} = 6.0\text{ V}$	-	0.16	0.26	-	0.33	-	0.4	V
$I_I$	input leakage current	$V_I = V_{CC}$ or GND; $V_{CC} = 6.0\text{ V}$	-	-	$\pm 0.1$	-	$\pm 1.0$	-	$\pm 1.0$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = V_{CC}$ or GND; $I_O = 0\text{ A};$ $V_{CC} = 6.0\text{ V}$	-	-	8.0	-	80	-	160	$\mu\text{A}$
$C_I$	input capacitance		-	3.5	-	-	-	-	-	pF

## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ °C}$			$T_{amb} = -40\text{ °C to }+85\text{ °C}$		$T_{amb} = -40\text{ °C to }+125\text{ °C}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_{pd}$	propagation delay	An to $Y_n$ ; see <a href="#">Figure 6</a> <sup>[1]</sup>								
		$V_{CC} = 2.0\text{ V}$	-	52	160	-	200	-	240	ns
		$V_{CC} = 4.5\text{ V}$	-	19	32	-	40	-	48	ns
		$V_{CC} = 5\text{ V}; C_L = 15\text{ pF}$	-	16	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	15	27	-	34	-	41	ns
		$\overline{LE}$ to $Y_n$ ; see <a href="#">Figure 6</a> <sup>[1]</sup>								
		$V_{CC} = 2.0\text{ V}$	-	61	190	-	240	-	285	ns
		$V_{CC} = 4.5\text{ V}$	-	22	38	-	48	-	57	ns
		$V_{CC} = 5\text{ V}; C_L = 15\text{ pF}$	-	19	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	18	32	-	41	-	48	ns
		$\overline{E}1$ to $Y_n$ ; see <a href="#">Figure 7</a> <sup>[1]</sup>								
		$V_{CC} = 2.0\text{ V}$	-	47	145	-	180	-	220	ns
		$V_{CC} = 4.5\text{ V}$	-	17	29	-	36	-	44	ns
		$V_{CC} = 5\text{ V}; C_L = 15\text{ pF}$	-	14	-	-	-	-	-	ns
		$V_{CC} = 6.0\text{ V}$	-	14	25	-	31	-	38	ns
		$t_t$	transition time	$E2$ to $Y_n$ ; see <a href="#">Figure 6</a> <sup>[1]</sup>						
$V_{CC} = 2.0\text{ V}$	-			47	145	-	180	-	220	ns
$V_{CC} = 4.5\text{ V}$	-			17	29	-	36	-	44	ns
$V_{CC} = 5\text{ V}; C_L = 15\text{ pF}$	-			14	-	-	-	-	-	ns
$V_{CC} = 6.0\text{ V}$	-			14	25	-	31	-	38	ns
$Y_n$ ; see <a href="#">Figure 6</a> and <a href="#">Figure 7</a> <sup>[2]</sup>										
$V_{CC} = 2.0\text{ V}$	-			19	75	-	95	-	110	ns
$V_{CC} = 4.5\text{ V}$	-			7	15	-	19	-	22	ns
$V_{CC} = 6.0\text{ V}$	-	6	13	-	16	-	19	ns		
$t_W$	pulse width	$\overline{LE}$ HIGH; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0\text{ V}$	50	11	-	65	-	75	-	ns
		$V_{CC} = 4.5\text{ V}$	10	4	-	13	-	15	-	ns
		$V_{CC} = 6.0\text{ V}$	9	3	-	11	-	13	-	ns
$t_{su}$	set-up time	An to $\overline{LE}$ ; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0\text{ V}$	50	6	-	65	-	75	-	ns
		$V_{CC} = 4.5\text{ V}$	10	2	-	13	-	15	-	ns
		$V_{CC} = 6.0\text{ V}$	9	2	-	11	-	13	-	ns

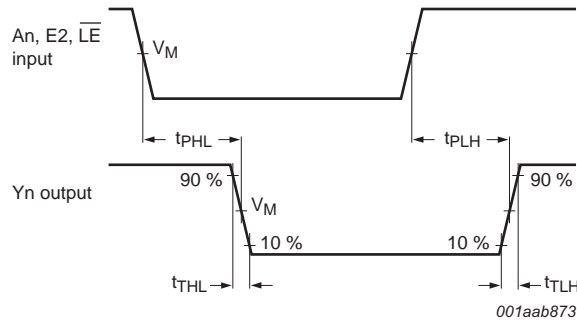
**Table 7. Dynamic characteristics ...continued**

Voltages are referenced to GND (ground = 0 V);  $C_L = 50$  pF unless otherwise specified; for test circuit see [Figure 9](#).

Symbol	Parameter	Conditions	$T_{amb} = 25\text{ }^\circ\text{C}$			$T_{amb} = -40\text{ }^\circ\text{C}$ to $+85\text{ }^\circ\text{C}$		$T_{amb} = -40\text{ }^\circ\text{C}$ to $+125\text{ }^\circ\text{C}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_h$	hold time	An to $\overline{LE}$ ; see <a href="#">Figure 8</a>								
		$V_{CC} = 2.0\text{ V}$	30	3	-	40	-	45	-	ns
		$V_{CC} = 4.5\text{ V}$	6	1	-	8	-	9	-	ns
		$V_{CC} = 6.0\text{ V}$	5	1	-	7	-	8	-	ns
$C_{PD}$	power dissipation capacitance	$C_L = 50\text{ pF}$ ; $f = 1\text{ MHz}$ ; $V_1 = \text{GND to } V_{CC}$	[9]	-	60	-	-	-	-	pF

- [1]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .
- [2]  $t_t$  is the same as  $t_{THL}$  and  $t_{TLH}$ .
- [3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ).  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \sum(C_L \times V_{CC}^2 \times f_o)$  where:  
 $f_i$  = input frequency in MHz;  
 $f_o$  = output frequency in MHz;  
 $C_L$  = output load capacitance in pF;  
 $V_{CC}$  = supply voltage in V;  
 $N$  = number of inputs switching;  
 $\sum(C_L \times V_{CC}^2 \times f_o)$  = sum of outputs.

## 11. Waveforms

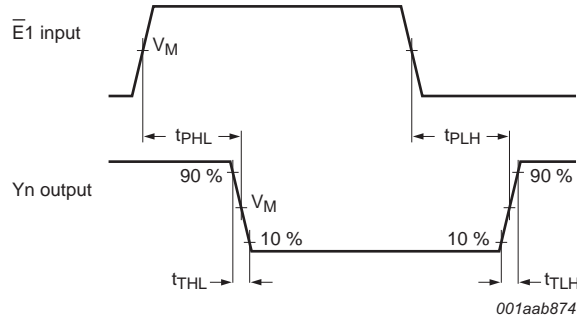


Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 6. Propagation delay input ( $A_n$ ) and enable inputs ( $E2$ ,  $\overline{LE}$ ) to output ( $Y_n$ ) and output transition time**

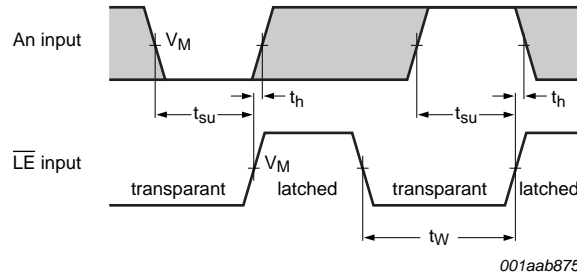




Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 7. Propagation enable inputs ( $\bar{E}1$ ) to output ( $Y_n$ ) and output transition time**



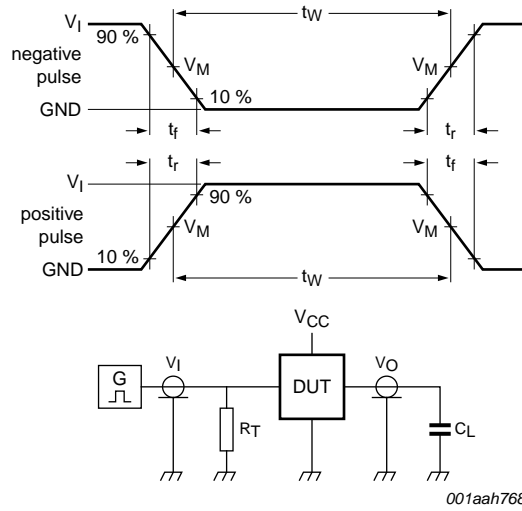
Measurement points are given in [Table 8](#).

$V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig 8. The data input ( $A_n$ ) to latch enable input ( $\bar{LE}$ ) set-up times, latch enable input ( $\bar{LE}$ ) to data input ( $A_n$ ) hold times and latch enable input ( $\bar{LE}$ ) pulse width**

**Table 8. Measurement points**

Type	Input	Output
	$V_M$	$V_M$
74HC237-Q100	$0.5V_{CC}$	$0.5V_{CC}$



Test data is given in [Table 9](#).

Definitions test circuit:

$R_T$  = Termination resistance should be equal to output impedance  $Z_o$  of the pulse generator.

$C_L$  = Load capacitance including jig and probe capacitance.

$R_L$  = Load resistance.

S1 = Test selection switch.

**Fig 9. Test circuit for measuring switching times**

**Table 9. Test data**

Type	Input		Load	Test
	$V_I$	$t_r, t_f$	$C_L$	
74HC237-Q100	$V_{CC}$	6.0 ns	15 pF, 50 pF	$t_{PLH}, t_{PHL}$

## 12. Application information

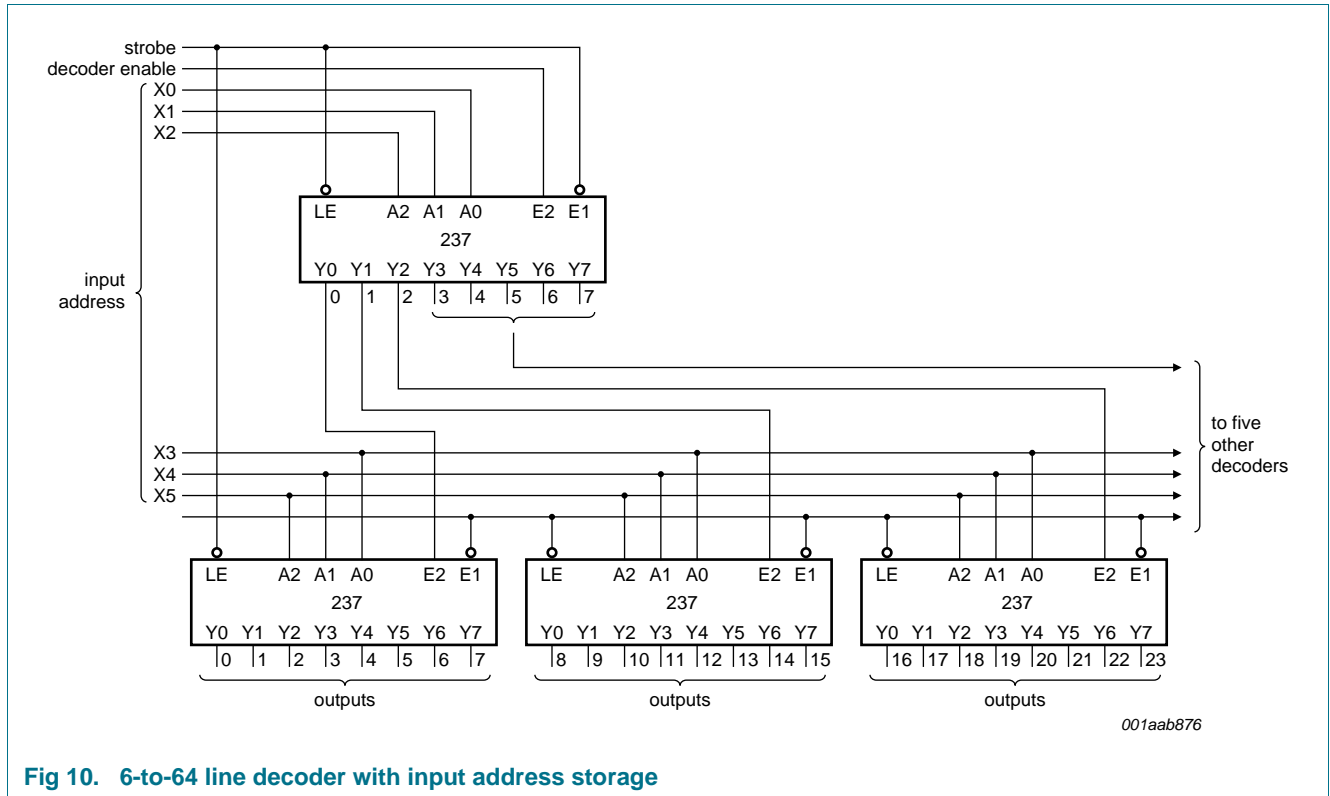


Fig 10. 6-to-64 line decoder with input address storage

13. Package outline

SO16: plastic small outline package; 16 leads; body width 3.9 mm

SOT109-1

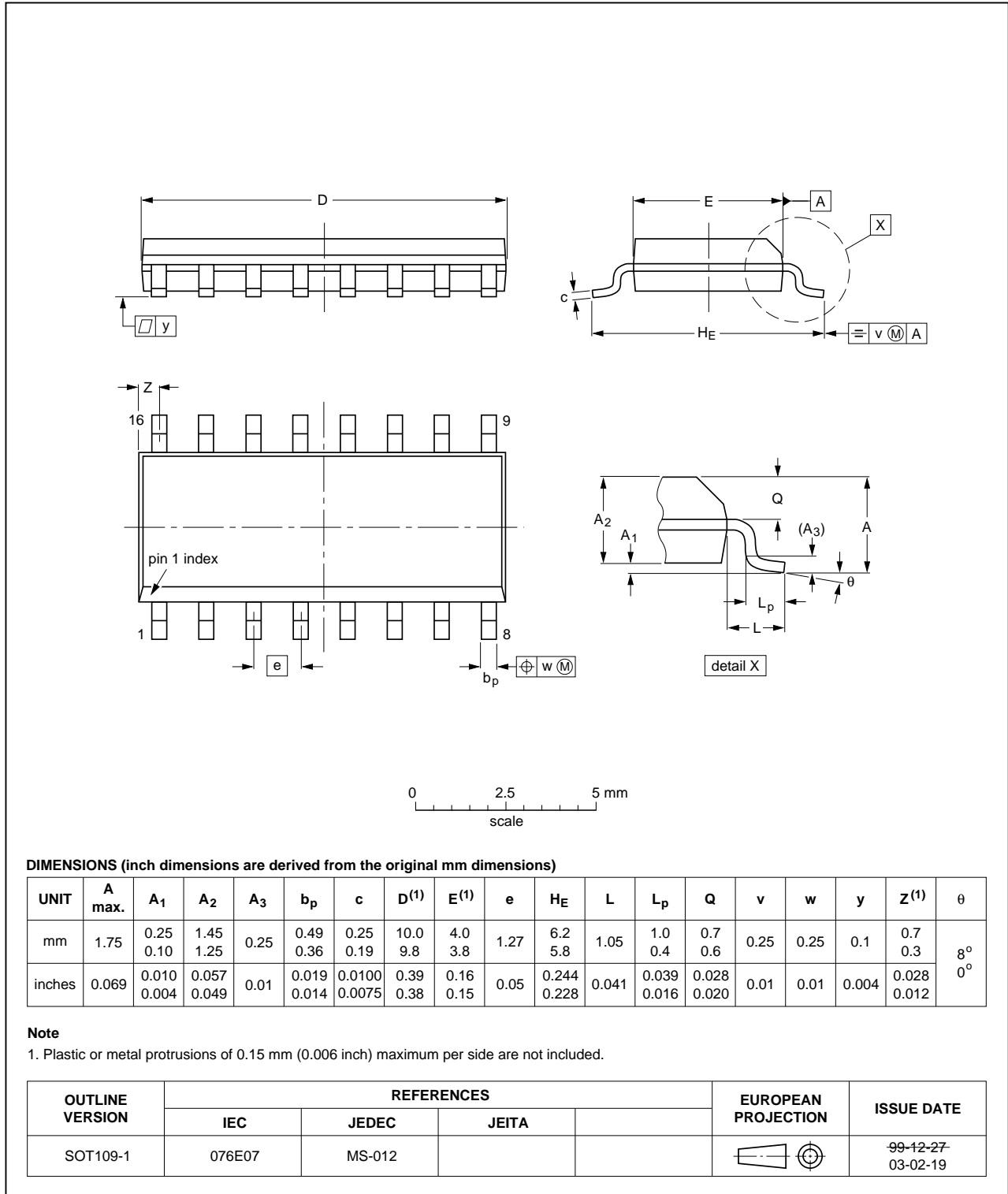


Fig 11. Package outline SOT109-1 (SO16)

## 14. Abbreviations

Table 10. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
MIL	Military
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 11. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74HC237_Q100 v.1	20130114	Product data sheet	-	-

## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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